

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2790111

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SAURABH SENSARMA	03/18/2014
ARVIND KULATHU RAMACHANDRAN	03/18/2014
SEYFULLAH HALIT OGUZ	03/21/2014
KHALED HELMI EL-MALEH	03/21/2014
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14216153
CORRESPONDENCE DATA	
Fax Number:	(408)720-8383
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(408) 720-8300
Email:	joan_abriam@bstz.com
Correspondent Name:	WILLIAM L. JAFFE
Address Line 1:	BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP
Address Line 2:	1279 OAKMEAD PARKWAY
Address Line 4:	SUNNYVALE, CALIFORNIA 94085
ATTORNEY DOCKET NUMBER:	133420
NAME OF SUBMITTER:	WILLIAM L. JAFFE
SIGNATURE:	/William L. Jaffe/
DATE SIGNED:	03/28/2014
Total Attachments: 5	
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ASSIGNMENT

WHEREAS, WE,

1. **Saurabh Sensharma**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California, U.S., 92121-1714, and a resident of Uttar Pradesh, India,
2. **Arvind Kulathu Ramachandran**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California, U.S., 92121-1714, and a resident of Kerala, India,
3. **Seyfullah Halit Oguz**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California, U.S., 92121-1714, and a resident of San Diego, California, U.S.,
4. **Khaled Helmi El-Maleh**, a citizen of Canada, having a mailing address located at 5775 Morehouse Drive, San Diego, California, U.S., 92121-1714, and a resident of San Marcos, California, U.S.,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **METHOD AND APPARATUS FOR AUTHENTICATING A USER ON A MOBILE DEVICE** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/216,153, filed March 17, 2014, Qualcomm Reference No. 133420, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all

reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I further do acknowledge and agree that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

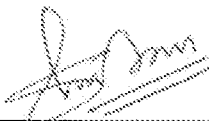
AND I DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND I DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I may be entitled, or that I may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I HEREBY covenant and agree that I will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at HYDERABAD, on 18th March 2014
LOCATION DATE




Saurabh Sensharma

PATENT

QUALCOMM Ref. No. 133420

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Done at HYDERABAD, on 18th March 2014
LOCATION DATE


Arvind Kulathu Ramachandran

Done at _____, on _____
LOCATION DATE

Seyfullah Halit Oguz

Done at _____, on _____
LOCATION DATE

Khaled Helmi El-Maleh

Inventor

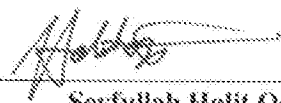
PATENT

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Done at _____, on _____
LOCATION DATE

Arvind Kulathu Ramachandran

Done at San Diego, on 3/21/2014
LOCATION DATE




Seyfullah Halit Oguz

Done at _____, on _____
LOCATION DATE

Khaled Helmi El-Maleh

Done at _____, on _____
LOCATION DATE Aryind Kulathu Ramachandran

Done at _____, on _____
LOCATION DATE Seyfullah Halit Oguz

Done at San Diego, on 21st March 14'
LOCATION DATE 
Khaled Helmi El-Maleh